

L Number	Hits	Search Text	DB	Time stamp
1	2	((("6613685") or ("6183565")).PN.	USPAT; US-PGPUB	2004/01/06 11:51
2	22	("3854443"   "3947236"   "4495024"   "4560590"   "4574093"   "4575408"   "4622918"   "4662987"   "4903717"   "4958061"   "5318801"   "5356476"   "5431700"   "5447431"   "5520536"   "5542559"   "5772770"   "5778968"   "5881208"   "5927077"   "5937541"   "5960159").PN.	USPAT	2004/01/06 12:48
3	27	("3854443"   "3947236"   "4495024"   "4560590"   "4574093"   "4575408"   "4622918"   "4662987"   "4903717"   "4903754"   "4958061"   "5318801"   "5356476"   "5431700"   "5447431"   "5520538"   "5542559"   "5772770"   "5778968"   "5881208"   "5927077"   "5937541"   "5960159"   "5997588"   "6001175"   "6099056"   "6183565").PN.	USPAT	2004/01/06 13:00
4	0	6613685.URPN.	USPAT	2004/01/06 13:25
5	4	6183565.URPN.	USPAT	2004/01/06 13:26
6	0	6461439.URPN.	USPAT	2004/01/06 13:31
7	25	("3854443"   "3947236"   "4495024"   "4560590"   "4574093"   "4575408"   "4662918"   "4662987"   "4903717"   "4903754"   "4958061"   "5318801"   "5356476"   "5431700"   "5447431"   "5520538"   "5542559"   "5772770"   "5778968"   "5881208"   "5927077"   "5937541"   "5960159"   "6099056"   "6183565").PN.	USPAT	2004/01/06 13:31
8	25	("3854443"   "3947236"   "4495024"   "4560590"   "4574093"   "4575408"   "4662918"   "4662987"   "4903717"   "4903754"   "4958061"   "5318801"   "5356476"   "5431700"   "5447431"   "5520538"   "5542559"   "5772770"   "5778968"   "5881208"   "5927077"   "5937541"   "5960159"   "6099056"   "6183565").PN.	USPAT	2004/01/06 13:34
9	1940	((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:23
10	122	((((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece))) and (heat or heating or heated).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 13:50
11	0	20020002951.URPN.	USPAT	2004/01/06 13:57
12	6	("4495024"   "4560590"   "4575408"   "5314848"   "6018616"   "6097005").PN.	USPAT	2004/01/06 14:04
13	160	((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:23
14	160	((((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.) not (("4495024"   "4560590"   "4575408"   "5314848"   "6018616"   "6097005").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:23
15	160	((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:24
16	130	((((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.) not (((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece))) and (heat or heating or heated).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:27
17	1688	((((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece))) not (((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.) or (((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece))) and (heat or heating or heated).clm.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 14:30

-	127	(float\$ adj wafer)	USPAT	2004/01/06 13:35
-	755	(float\$ adj (wafer or substrate or workpiece))	USPAT; JPO; DERWENT	2001/07/31 17:45
-	6	((float\$ adj (wafer or substrate or workpiece)) ) and (pulse same energy)	USPAT; JPO; DERWENT	2001/07/31 17:46
-	93	((float\$ adj (wafer or substrate or workpiece)) ) and pulse	USPAT; JPO; DERWENT	2001/07/31 17:48